

# ATE/BURN-IN PCB

## CAPABILITIES

Layers	2 - 80L	Inner Layer Spacing Pad/Trace	1.5 mil
Max Board Size	15.75" x 30.0"	Aspect Ratio Mechanical	42:1
Board Thickness	.093" - .250"	Stub Drilling Max Depth	0.30 (.3mm pitch) - 0.130 (.5mm pitch)
DUT/Drill Pattern Pitch	.0118" (.3mm) minimum	Stub Drill Diameter	0.0079 (.3mm pitch) - 0.01 (.5mm pitch)
Min. Line Width	2.5 mil	Surface Finish	ENIG   ENIPIG   Hard Gold Selective Gold   Flash Gold
Min. Line Space	2.5 mil	Impedance Control	≤50 OHMS = ±5 OHMS >50 OHMS = ±10%
Min. Mechanical Drill/Pad	4 mil   10 mil		
Min. Laser Drill/Pad	3 mil   6 mil		

## SURFACE FINISHES

- HASL/LF HASL
- ENIG
- ENEPIG
- OSP

## MATERIALS

### Standard FR-4 (high Tg, high Td)

- Panasonic R-1755S
- MGC EL-190T
- Hitachi MCL-E-679W
- Hitachi MCL-E-679FJ
- Hitachi MCL-E-75G

### Low Dk/Df for High Speed/High Frequency

- Panasonic R-5725 (Megtron4)
- Panasonic R-5775 (Megtron6)
- Panasonic R-5785(N) (Megtron7 LD)
- MGC EL-230T
- Hitachi HE-679G
- Hitachi HE-679GS
- AGC (Park Electrochemical) Meteorwave 4000
- Rogers RO4350B

## LEAD TIMES

Lead times vary widely depending on material selection and technology level.

Lead time can be evaluated at time of quote.

